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## TABLE OF CONTENTS

<b>Characterisation of PZT in Thin Film Bulk Acoustic Wave Resonators</b> .....	1
<i>J. Conde, P. Murali</i>	
<b>Stacked Boron Doped Poly-Crystalline Silicon-Germanium Layers: an Excellent MEMS Structural Material</b> .....	7
<i>G. Claes, G. Van Barel, R. Van Hoof, B. Du Bois, M. Gromova, A. Verbist, T. Van Der Donck, S. Decoutere, J. Celis, A. Witvrouw</i>	
<b>Microstructural Evolution of SiC Fibre Embedded AA6061 Matrix Induced by Ultrasonic Consolidation</b> .....	13
<i>Z. Zhu, B.P. Wynne, E. Ghassemieh</i>	
<b>Effects of Sputtering Metal Deposition Parameters in the Photoresist used as a Sacrificial Layer in Micro-electromechanical System Devices</b> .....	19
<i>D. Molinero</i>	
<b>Low-Power Liquid Lens Having Si Cylinder Chamber for Capsule Endoscope</b> .....	25
<i>S. Seo, S. Han, J. Seo, Y. Kim, M. Kang, N. Min, W. Choi, M. Sung</i>	
<b>UV Laser Ablation of PLZT and PSZT Films</b> .....	31
<i>P.W. Leech, A.S. Holland, S. Sriram, M. Bhaskaran</i>	
<b>High-Speed, High-Sensitivity Polyimide Humidity Sensors Based on MEMS Microhotplates</b> .....	37
<i>J.S. Kim, T.J. Kim, M.S. Kang, K.P. Yoo, N.K. Min</i>	
<b>Integrated (Ba,Sr)TiO<sub>3</sub> Thin-Film Technology for RF and Microwave Applications</b> .....	43
<i>T. Suzuki, D. Ishii, Y. Iwazaki, K. Morito, Y. Mizuno</i>	
<b>The Road To Flexible Mems Integration</b> .....	55
<i>A. Witvrouw</i>	
<b>Dispersive Evaluation and Self-Sensing of Single Carbon Fiber/CNT-Epoxy Composites using Electro-Micromechanical Techniques</b> .....	67
<i>J. Park, J. Jang, Z. Wang, P. Kim, W. Lee, J. Park, L.K. DeVries</i>	
<b>Dielectric Charging in Low Temperature Silicon Nitride for RF-MEMS Capacitive Switches</b> .....	78
<i>R. Daigler, G. Papaioannou, E. Papandreou, J. Papapolymerou</i>	
<b>Thick Film Capacitors with Variable Tc on Cu Foils</b> .....	85
<i>B.K. Kim, D.J. Shin, J.K. Song, Y.S. Cho</i>	
<b>RF SOP (System On Package) Using Passive Embedded Substrate</b> .....	91
<i>N. Kang, J. Kim, D. Kim, C. Yoo, J. Ryu, H. Cho</i>	
<b>Piezoelectric Materials for Advanced Integrated RF Components</b> .....	102
<i>M. Al Ahmad, F. Coccetti, R. Plana</i>	

<b>Tunable Thin Film Integrated Material Characterizations for Microwave Applications .....</b>	<b>114</b>
<i>M. Al Ahmad, S. Payan, D. Michau, M. Maglione, R. Plana</i>	
<b>Mechanical Integrity of Hybrid Components used in Flexible Optoelectronic Devices.....</b>	<b>121</b>
<i>K.A. Sierros, N.J. Morris, J.S. Abell, D.R. Cairns, S.N. Kukureka</i>	
<b>Author Index</b>	